

## FEATURES

- Member of the Texas Instruments Widebus+™ Family
- Control Inputs  $V_{IH}/V_{IL}$  Levels Are Referenced to  $V_{CCA}$  Voltage
- $V_{CC}$  Isolation Feature – If Either  $V_{CC}$  Input Is at GND, Both Ports Are in the High-Impedance State
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over Full 1.2-V to 3.6-V Power-Supply Range
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- I/Os Are 4.6-V Tolerant
- Max Data Rates
  - 380 Mbps (1.8-V to 3.3-V Translation)
  - 200 Mbps (< 1.8-V to 3.3-V Translation)
  - 200 Mbps (Translate to 2.5 V or 1.8V)
  - 150 Mbps (Translate to 1.5 V)
  - 100 Mbps (Translate to 1.2 V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 4000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION/ORDERING INFORMATION

This 32-bit noninverting bus transceiver uses two separate configurable power-supply rails. The SN74AVC32T245 is optimized to operate with  $V_{CCA}/V_{CCB}$  set at 1.4 V to 3.6 V. It is operational with  $V_{CCA}/V_{CCB}$  as low as 1.2 V. The A port is designed to track  $V_{CCA}$ .  $V_{CCA}$  accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track  $V_{CCB}$ .  $V_{CCB}$  accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVC32T245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVC32T245 is designed so that the control pins (1DIR, 2DIR, 3DIR, 4DIR,  $1\overline{OE}$ ,  $2\overline{OE}$ ,  $3\overline{OE}$ , and  $4\overline{OE}$ ) are supplied by  $V_{CCA}$ .

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The  $V_{CC}$  isolation feature ensures that if either  $V_{CC}$  input is at GND, then both ports are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

## ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	LFBGA – GKE	Tape and reel	SN74AVC32T245GKER	WY245
	LFBGA – ZKE (Pb-free)		SN74AVC32T245ZKER	
	LFBGA – ZRL (Pb-free)		SN74AVC32T245ZRLR	

(1) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

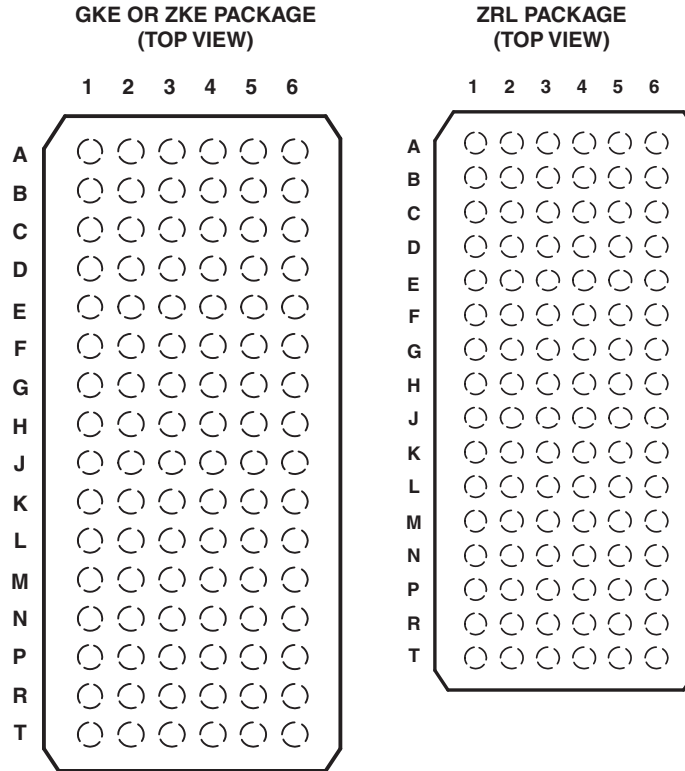


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Widebus+ is a trademark of Texas Instruments.

**SN74AVC32T245**  
**32-BIT DUAL-SUPPLY BUS TRANSCEIVER**  
**WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS**

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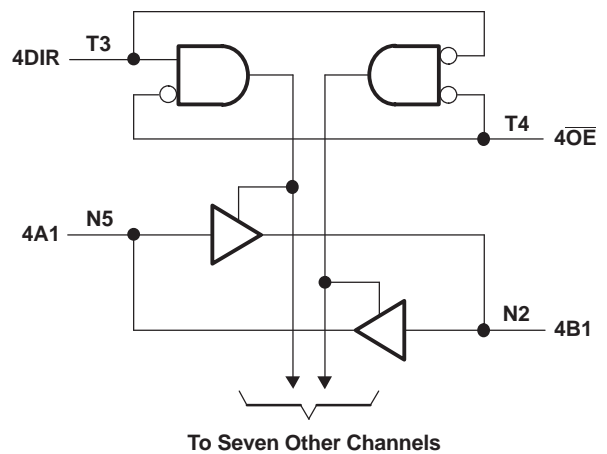
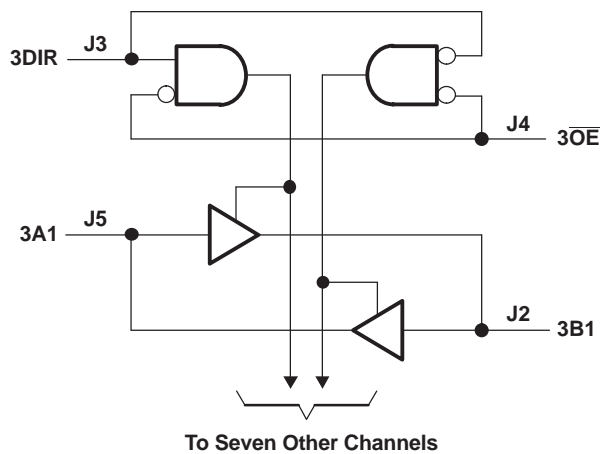
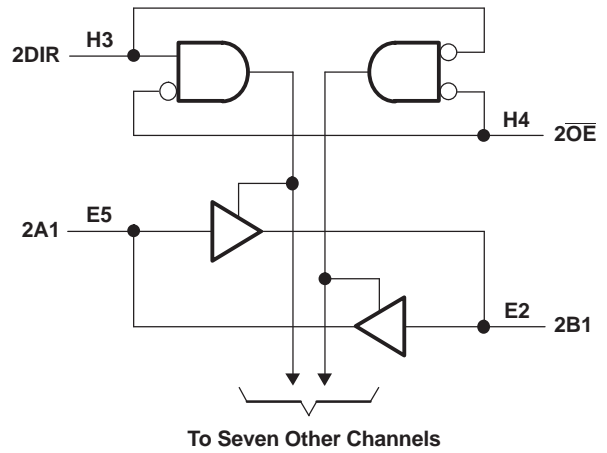
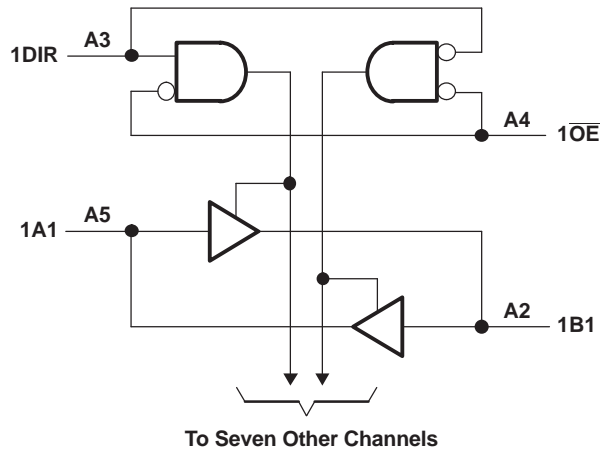
**TERMINAL ASSIGNMENTS**

	1	2	3	4	5	6
<b>A</b>	1B2	1B1	1DIR	1 $\overline{OE}$	1A1	1A2
<b>B</b>	1B4	1B3	GND	GND	1A3	1A4
<b>C</b>	1B6	1B5	V <sub>CCB</sub>	V <sub>CCA</sub>	1A5	1A6
<b>D</b>	1B8	1B7	GND	GND	1A7	1A8
<b>E</b>	2B2	2B1	GND	GND	2A1	2A2
<b>F</b>	2B4	2B3	V <sub>CCB</sub>	V <sub>CCA</sub>	2A3	2A4
<b>G</b>	2B6	2B5	GND	GND	2A5	2A6
<b>H</b>	2B7	2B8	2DIR	2 $\overline{OE}$	2A8	2A7
<b>J</b>	3B2	3B1	3DIR	3 $\overline{OE}$	3A1	3A2
<b>K</b>	3B4	3B3	GND	GND	3A3	3A4
<b>L</b>	3B6	3B5	V <sub>CCB</sub>	V <sub>CCA</sub>	3A5	3A6
<b>M</b>	3B8	3B7	GND	GND	3A7	3A8
<b>N</b>	4B2	4B1	GND	GND	4A1	4A2
<b>P</b>	4B4	4B3	V <sub>CCB</sub>	V <sub>CCA</sub>	4A3	4A4
<b>R</b>	4B6	4B5	GND	GND	4A5	4A6
<b>T</b>	4B7	4B8	4DIR	4 $\overline{OE}$	4A8	4A7

**FUNCTION TABLE**  
**(EACH 8-BIT SECTION)**

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

**LOGIC DIAGRAM (POSITIVE LOGIC)**



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**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
$V_{CCA}$ $V_{CCB}$	Supply voltage range	-0.5	4.6	V	
$V_I$	Input voltage range <sup>(2)</sup>	I/O ports (A port)	-0.5	4.6	V
		I/O ports (B port)	-0.5	4.6	
		Control inputs	-0.5	4.6	
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	A port	-0.5	4.6	V
		B port	-0.5	4.6	
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	A port	-0.5	$V_{CCA} + 0.5$	V
		B port	-0.5	$V_{CCB} + 0.5$	
$I_{IK}$	Input clamp current	$V_I < 0$	-50	mA	
$I_{OK}$	Output clamp current	$V_O < 0$	-50	mA	
$I_O$	Continuous output current		±50	mA	
		Continuous current through each $V_{CCA}$ , $V_{CCB}$ , and GND	±100	mA	
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	GKE/ZKE package	40	°C/W	
		ZRL package	TBD		
$T_{stg}$	Storage temperature range	-65	150	°C	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

**Recommended Operating Conditions**<sup>(1)(2)(3)</sup>

		$V_{CCI}$	$V_{CCO}$	MIN	MAX	UNIT
$V_{CCA}$	Supply voltage			1.2	3.6	V
$V_{CCB}$	Supply voltage			1.2	3.6	V
$V_{IH}$	High-level input voltage	Data inputs <sup>(4)</sup>	1.2 V to 1.95 V	$V_{CCI} \times 0.65$		V
			1.95 V to 2.7 V	1.6		
			2.7 V to 3.6 V	2		
$V_{IL}$	Low-level input voltage	Data inputs <sup>(4)</sup>	1.2 V to 1.95 V	$V_{CCI} \times 0.35$		V
			1.95 V to 2.7 V	0.7		
			2.7 V to 3.6 V	0.8		
$V_{IH}$	High-level input voltage	DIR (referenced to $V_{CCA}$ ) <sup>(5)</sup>	1.2 V to 1.95 V	$V_{CCA} \times 0.65$		V
			1.95 V to 2.7 V	1.6		
			2.7 V to 3.6 V	2		
$V_{IL}$	Low-level input voltage	DIR (referenced to $V_{CCA}$ ) <sup>(5)</sup>	1.2 V to 1.95 V	$V_{CCA} \times 0.35$		V
			1.95 V to 2.7 V	0.7		
			2.7 V to 3.6 V	0.8		
$V_I$	Input voltage			0	3.6	V
$V_O$	Output voltage	Active state		0	$V_{CCO}$	V
		3-state		0	3.6	
$I_{OH}$	High-level output current		1.2 V	–3		mA
			1.4 V to 1.6 V	–6		
			1.65 V to 1.95 V	–8		
			2.3 V to 2.7 V	–9		
			3 V to 3.6 V	–12		
$I_{OL}$	Low-level output current		1.2 V	3		mA
			1.4 V to 1.6 V	6		
			1.65 V to 1.95 V	8		
			2.3 V to 2.7 V	9		
			3 V to 3.6 V	12		
$\Delta t/\Delta v$	Input transition rise or fall rate				5	ns/V
$T_A$	Operating free-air temperature			–40	85	°C

(1)  $V_{CCI}$  is the  $V_{CC}$  associated with the data input port.

(2)  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

(3) All unused data inputs of the device must be held at  $V_{CCI}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(4) For  $V_{CCI}$  values not specified in the data sheet,  $V_{IH}$  min =  $V_{CCI} \times 0.7$  V,  $V_{IL}$  max =  $V_{CCI} \times 0.3$  V.

(5) For  $V_{CCI}$  values not specified in the data sheet,  $V_{IH}$  min =  $V_{CCA} \times 0.7$  V,  $V_{IL}$  max =  $V_{CCA} \times 0.3$  V.

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**Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)<sup>(1)(2)</sup>

PARAMETER	TEST CONDITIONS		V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			-40°C TO 85°C		UNIT
					MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>		V <sub>I</sub> = V <sub>IH</sub>	1.2 V to 3.6 V	1.2 V to 3.6 V				V <sub>CCO</sub> – 0.2 V		V
			1.2 V	1.2 V	0.95					
			1.4 V	1.4 V				1.05		
			1.65 V	1.65 V				1.2		
			2.3 V	2.3 V				1.75		
			3 V	3 V				2.3		
V <sub>OL</sub>		V <sub>I</sub> = V <sub>IL</sub>	1.2 V to 3.6 V	1.2 V to 3.6 V				0.2		V
			1.2 V	1.2 V	0.15					
			1.4 V	1.4 V				0.35		
			1.65 V	1.65 V				0.45		
			2.3 V	2.3 V				0.55		
			3 V	3 V				0.7		
I <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CCA</sub> or GND	1.2 V to 3.6 V	1.2 V to 3.6 V	±0.025	±0.25		±1	µA	
I <sub>off</sub>	A or B port	V <sub>I</sub> or V <sub>O</sub> = 0 to 3.6 V	0 V	0 to 3.6 V	±0.1	±2.5		±5	µA	
	A or B port		0 to 3.6 V	0 V	±0.1	±2.5		±5		
I <sub>OZ</sub> <sup>(3)</sup>	A or B port	V <sub>O</sub> = V <sub>CCO</sub> or GND, V <sub>I</sub> = V <sub>CC1</sub> or GND, OE = V <sub>IH</sub>	3.6 V	3.6 V	±0.5	±2.5		±5	µA	
I <sub>CCA</sub>		V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0	1.2 V to 3.6 V	1.2 V to 3.6 V				50	µA	
			0 V	3.6 V				–10		
			3.6 V	0 V				50		
I <sub>CCB</sub>		V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0	1.2 V to 3.6 V	1.2 V to 3.6 V				50	µA	
			0 V	3.6 V				50		
			3.6 V	0 V				–10		
I <sub>CCA</sub> + I <sub>CCB</sub>		V <sub>I</sub> = V <sub>CC1</sub> or GND, I <sub>O</sub> = 0	1.2 V to 3.6 V	1.2 V to 3.6 V				90	µA	
C <sub>i</sub>	Control inputs	V <sub>I</sub> = 3.3 V or GND	3.3 V	3.3 V	3.5				pF	
C <sub>io</sub>	A or B port	V <sub>O</sub> = 3.3 V or GND	3.3 V	3.3 V	7				pF	

- (1) V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.  
(2) V<sub>CC1</sub> is the V<sub>CC</sub> associated with the input port.  
(3) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

## Switching Characteristics

 over recommended operating free-air temperature range,  $V_{CCA} = 1.2\text{ V}$  (see [Figure 11](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2\text{ V}$	$V_{CCB} = 1.5\text{ V}$	$V_{CCB} = 1.8\text{ V}$	$V_{CCB} = 2.5\text{ V}$	$V_{CCB} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	TYP	TYP	
$t_{PLH}$	A	B	4.1	3.3	3	2.8	3.2	ns
$t_{PHL}$			4.1	3.3	3	2.8	3.2	
$t_{PLH}$	B	A	4.4	4	3.8	3.6	3.5	ns
$t_{PHL}$			4.4	4	3.8	3.6	3.5	
$t_{PZH}$	$\overline{OE}$	A	6.4	6.4	6.4	6.4	6.4	ns
$t_{PZL}$			6.4	6.4	6.4	6.4	6.4	
$t_{PZH}$	$\overline{OE}$	B	6	4.6	4	3.4	3.2	ns
$t_{PZL}$			6	4.6	4	3.4	3.2	
$t_{PHZ}$	$\overline{OE}$	A	6.6	6.6	6.6	6.6	6.8	ns
$t_{PLZ}$			6.6	6.6	6.6	6.6	6.8	
$t_{PHZ}$	$\overline{OE}$	B	6	4.9	4.9	4.2	5.3	ns
$t_{PLZ}$			6	4.9	4.9	4.2	5.3	

## Switching Characteristics

 over recommended operating free-air temperature range,  $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$  (see [Figure 11](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2\text{ V}$	$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$		$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	ns
$t_{PHL}$			3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	
$t_{PLH}$	B	A	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	ns
$t_{PHL}$			3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	
$t_{PZH}$	$\overline{OE}$	A	4.3	1	10.1	1	10.1	1	10.1	1	10.1	ns
$t_{PZL}$			4.3	1	10.1	1	10.1	1	10.1	1	10.1	
$t_{PZH}$	$\overline{OE}$	B	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	ns
$t_{PZL}$			5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	
$t_{PHZ}$	$\overline{OE}$	A	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	ns
$t_{PLZ}$			4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	
$t_{PHZ}$	$\overline{OE}$	B	5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	ns
$t_{PLZ}$			5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	

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**Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$  (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2\text{ V}$	$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$		$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	ns
$t_{PHL}$			3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	
$t_{PLH}$	B	A	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	ns
$t_{PHL}$			3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	
$t_{PZH}$	$\overline{OE}$	A	3.4	1	7.8	1	7.8	1	7.8	1	7.8	ns
$t_{PZL}$			3.4	1	7.8	1	7.8	1	7.8	1	7.8	
$t_{PZH}$	$\overline{OE}$	B	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	ns
$t_{PZL}$			5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	
$t_{PHZ}$	$\overline{OE}$	A	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	ns
$t_{PLZ}$			4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	
$t_{PHZ}$	$\overline{OE}$	B	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	ns
$t_{PLZ}$			5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	

**Switching Characteristics**

over recommended operating free-air temperature range,  $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$  (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2\text{ V}$	$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$		$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	ns
$t_{PHL}$			3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	
$t_{PLH}$	B	A	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	ns
$t_{PHL}$			2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	
$t_{PZH}$	$\overline{OE}$	A	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	ns
$t_{PZL}$			2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	
$t_{PZH}$	$\overline{OE}$	B	5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	ns
$t_{PZL}$			5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	
$t_{PHZ}$	$\overline{OE}$	A	3	1	6.1	1	6.1	1	6.1	1	6.1	ns
$t_{PLZ}$			3	1	6.1	1	6.1	1	6.1	1	6.1	
$t_{PHZ}$	$\overline{OE}$	B	5	1	7.9	1	6.6	1	6.1	1	5.2	ns
$t_{PLZ}$			5	1	7.9	1	6.6	1	6.1	1	5.2	

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$  (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2 \text{ V}$	$V_{CCB} = 1.5 \text{ V} \pm 0.1 \text{ V}$		$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	ns
$t_{PHL}$			3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	
$t_{PLH}$	B	A	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	ns
$t_{PHL}$			2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	
$t_{PZH}$	$\overline{OE}$	A	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	ns
$t_{PZL}$			2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	
$t_{PZH}$	$\overline{OE}$	B	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	ns
$t_{PZL}$			5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	
$t_{PHZ}$	$\overline{OE}$	A	3.4	0.5	5	0.5	5	0.5	5	0.5	5	ns
$t_{PLZ}$			3.4	0.5	5	0.5	5	0.5	5	0.5	5	
$t_{PHZ}$	$\overline{OE}$	B	4.9	1	7.7	1	6.5	1	5.2	0.5	5	ns
$t_{PLZ}$			4.9	1	7.7	1	6.5	1	5.2	0.5	5	

## Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS	$V_{CCA} = V_{CCB} = 1.2 \text{ V}$	$V_{CCA} = V_{CCB} = 1.5 \text{ V}$	$V_{CCA} = V_{CCB} = 1.8 \text{ V}$	$V_{CCA} = V_{CCB} = 2.5 \text{ V}$	$V_{CCA} = V_{CCB} = 3.3 \text{ V}$	UNIT
				TYP	TYP	TYP	TYP	TYP	
$C_{pdA}^{(1)}$	A to B	Outputs enabled	$C_L = 0,$ $f = 10 \text{ MHz},$ $t_r = t_f = 1 \text{ ns}$	1	1	1	1	2	pF
		Outputs disabled		1	1	1	1	1	
	B to A	Outputs enabled		13	13	14	15	16	
		Outputs disabled		1	1	1	1	1	
$C_{pdB}^{(1)}$	A to B	Outputs enabled	$C_L = 0,$ $f = 10 \text{ MHz},$ $t_r = t_f = 1 \text{ ns}$	13	13	14	15	16	pF
		Outputs disabled		1	1	1	1	1	
	B to A	Outputs enabled		1	1	1	1	2	
		Outputs disabled		1	1	1	1	1	

(1) Power dissipation capacitance per transceiver

Table 1. Typical Total Static Power Consumption ( $I_{CCA} + I_{CCB}$ )

$V_{CCB}$	$V_{CCA}$						UNIT
	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
0 V	0	<1	<1	<1	<1	<1	$\mu\text{A}$
1.2 V	<1	<2	<2	<2	<2	2	
1.5 V	<1	<2	<2	<2	<2	2	
1.8 V	<1	<2	<2	<2	<2	<2	
2.5 V	<1	2	<2	<2	<2	<2	
3.3 V	<1	2	<2	<2	<2	<2	

TYPICAL CHARACTERISTICS

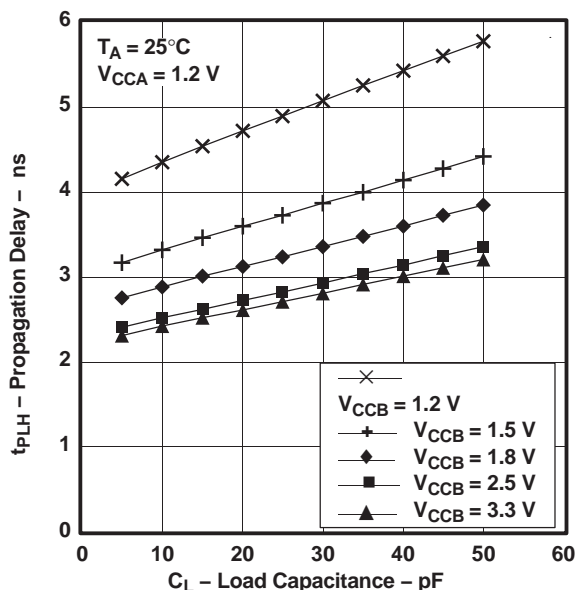


Figure 1.

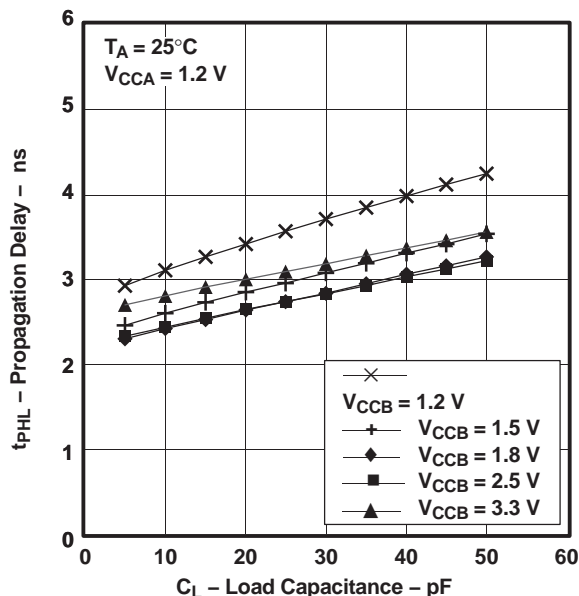


Figure 2.

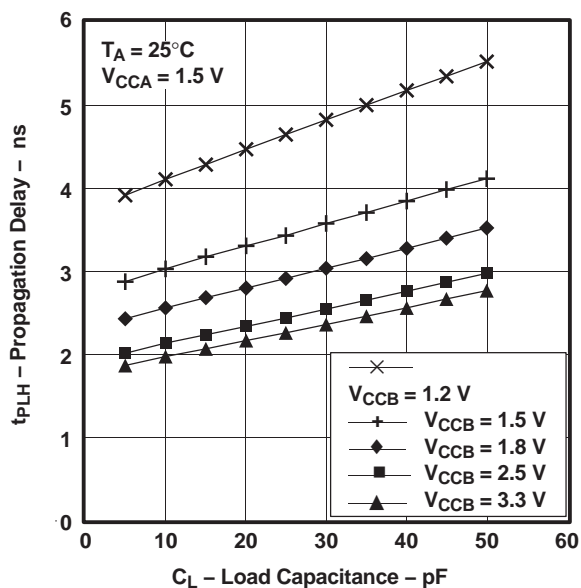


Figure 3.

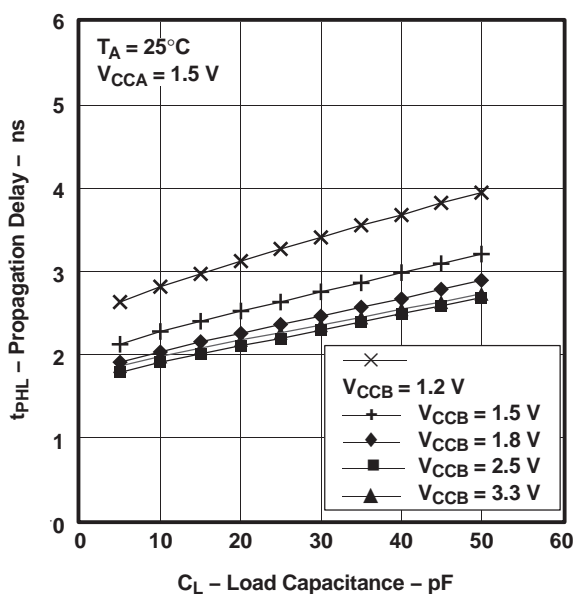


Figure 4.

**TYPICAL CHARACTERISTICS (continued)**

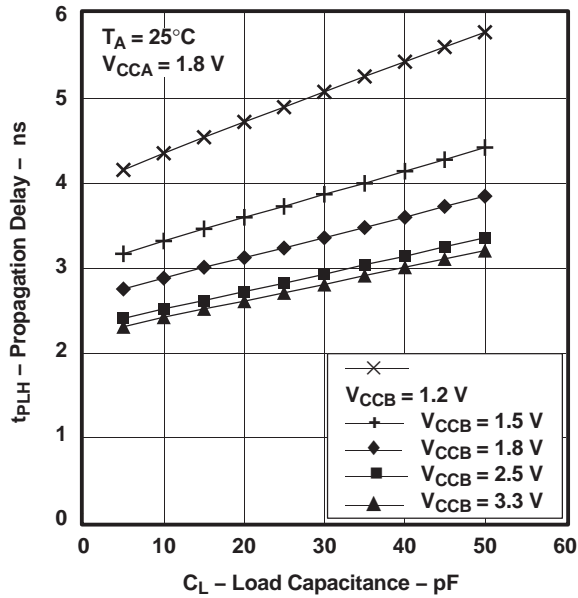


Figure 5.

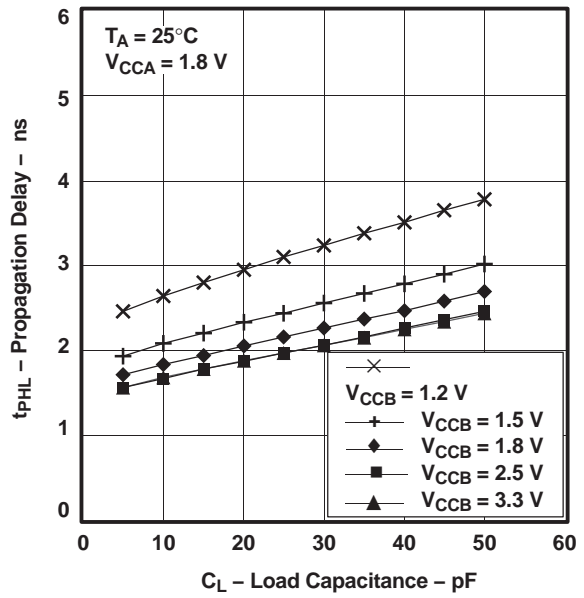


Figure 6.

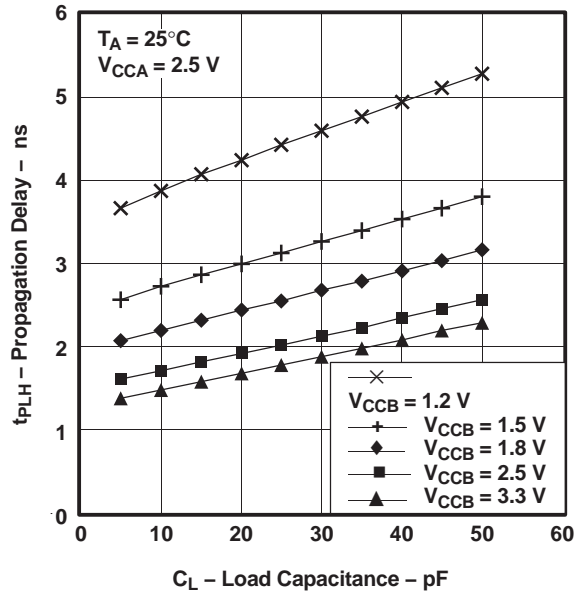


Figure 7.

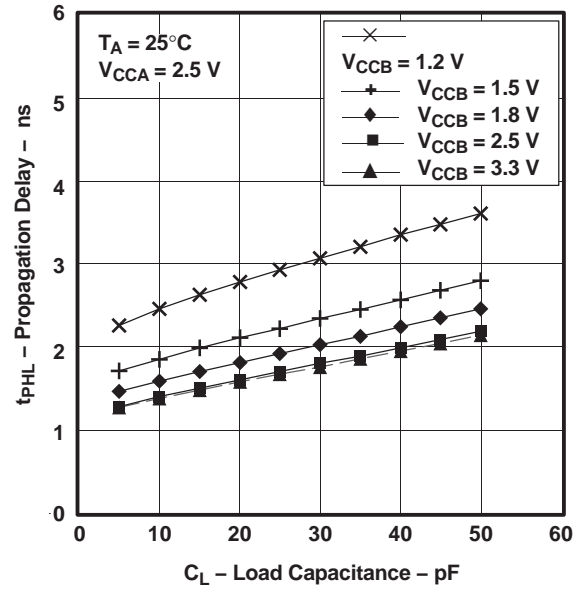


Figure 8.

TYPICAL CHARACTERISTICS (continued)

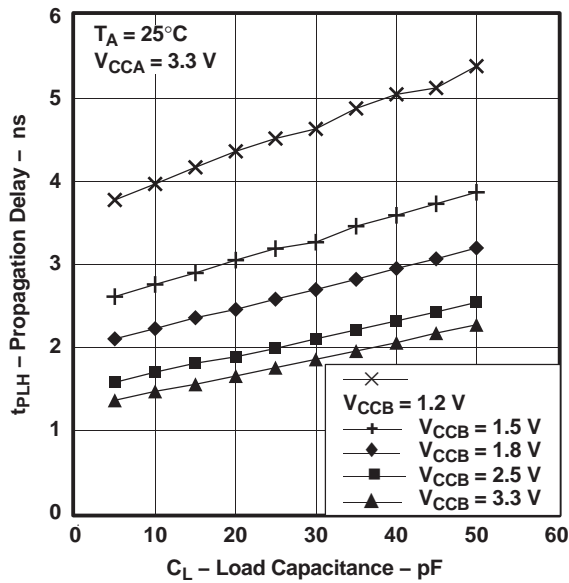


Figure 9.

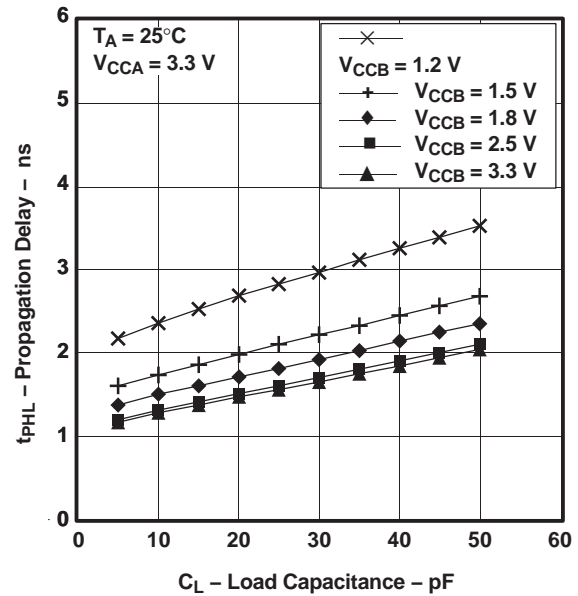
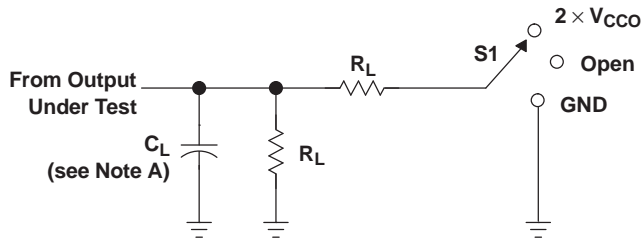


Figure 10.

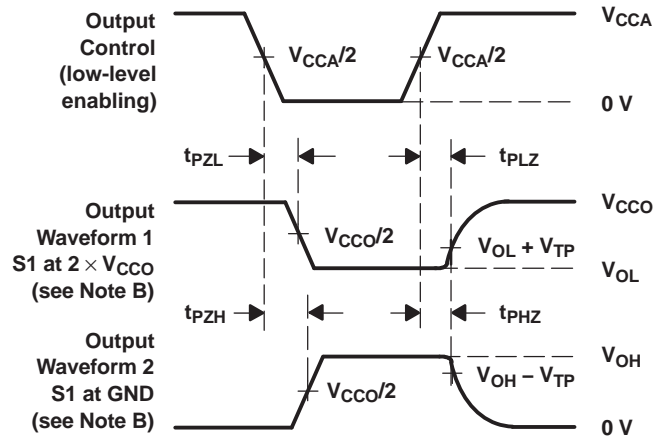
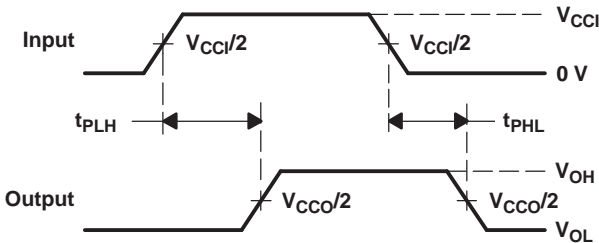
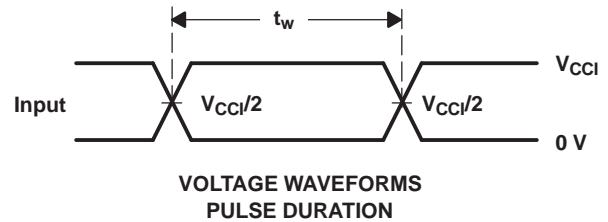
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CCO}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CCO}$	$C_L$	$R_L$	$V_{TP}$
1.2 V	15 pF	2 k $\Omega$	0.1 V
1.5 V $\pm$ 0.1 V	15 pF	2 k $\Omega$	0.1 V
1.8 V $\pm$ 0.15 V	15 pF	2 k $\Omega$	0.15 V
2.5 V $\pm$ 0.2 V	15 pF	2 k $\Omega$	0.15 V
3.3 V $\pm$ 0.3 V	15 pF	2 k $\Omega$	0.3 V



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $dv/dt \geq 1$  V/ns.  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H.  $V_{CCi}$  is the  $V_{CC}$  associated with the input port.  
 I.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

Figure 11. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AVC32T245GKER	ACTIVE	LFBGA	GKE	96	1000	TBD	SNPB	Level-2-235C-1 YEAR
SN74AVC32T245ZKER	ACTIVE	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR
SN74AVC32T245ZRLR	ACTIVE	BGA MI CROSTA R JUNI OR	ZRL	96	2500	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

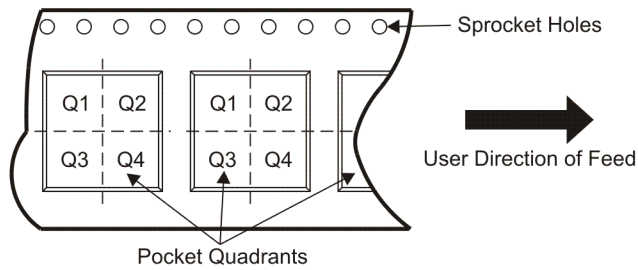
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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVC32T245GKER	LFBGA	GKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1
SN74AVC32T245ZKER	LFBGA	ZKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

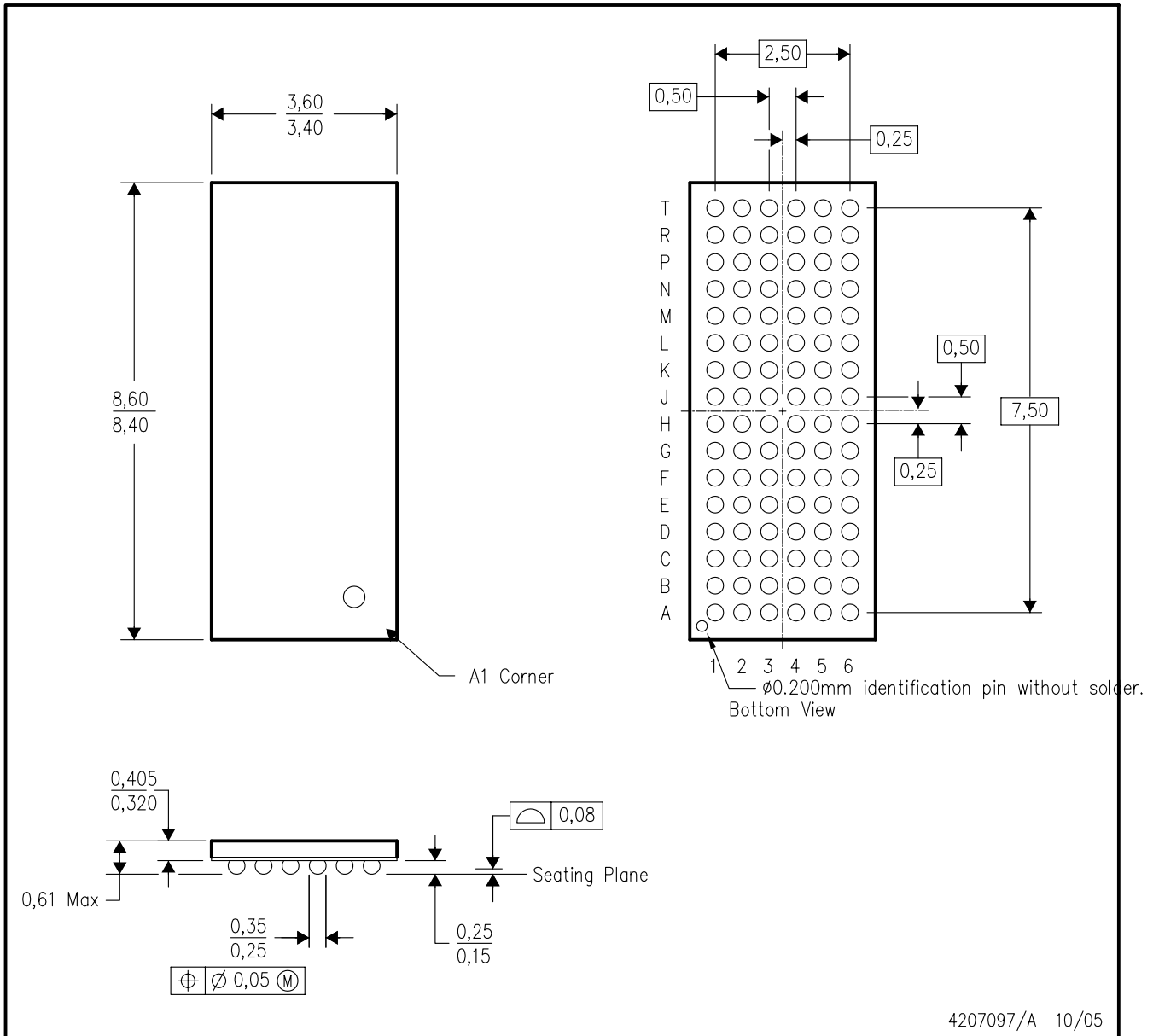


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVC32T245GKER	LFBGA	GKE	96	1000	346.0	346.0	41.0
SN74AVC32T245ZKER	LFBGA	ZKE	96	1000	346.0	346.0	41.0

ZRL (R-PBGA-N96)

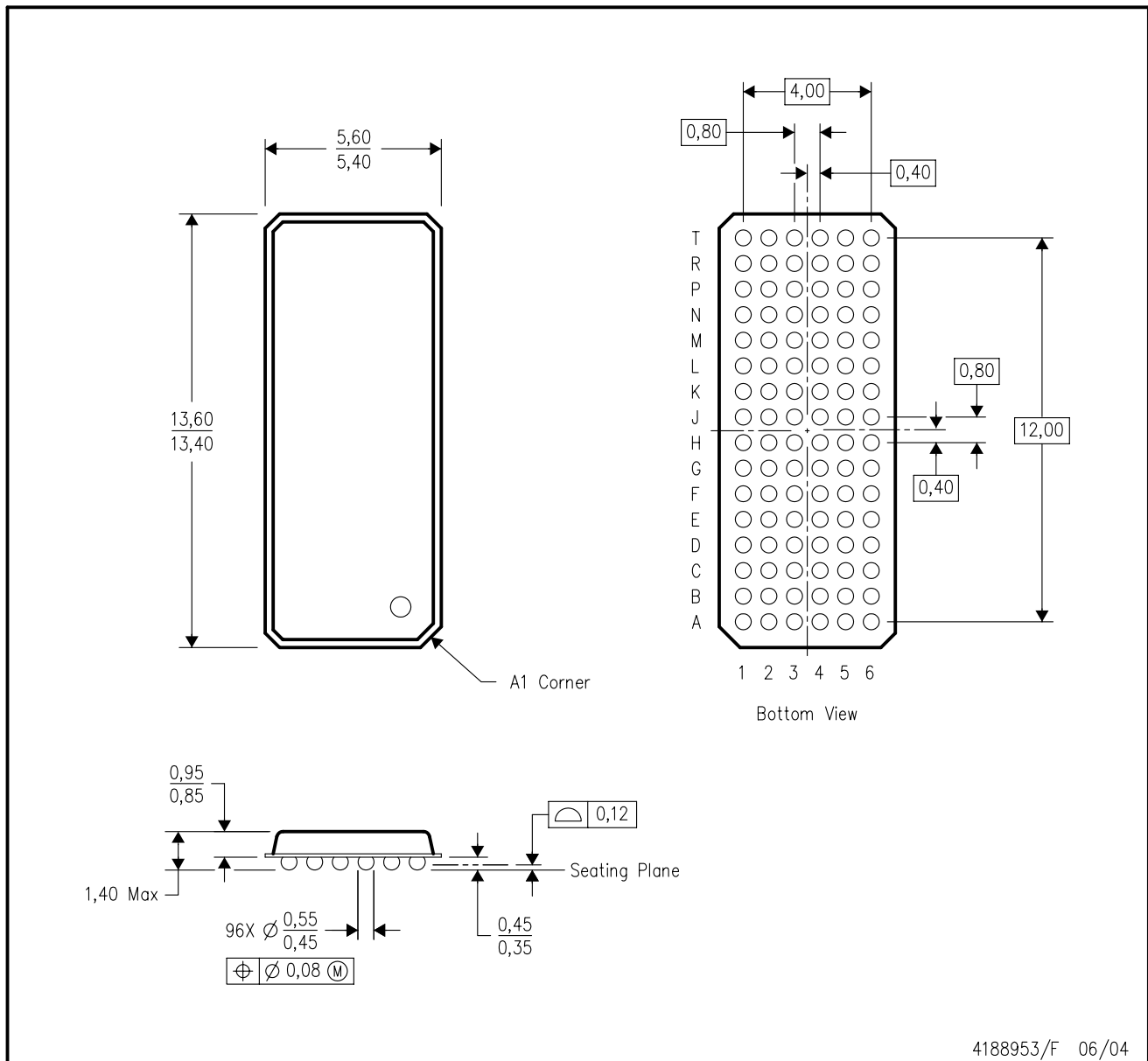
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. This is a lead-free solder ball design.

GKE (R-PBGA-N96)

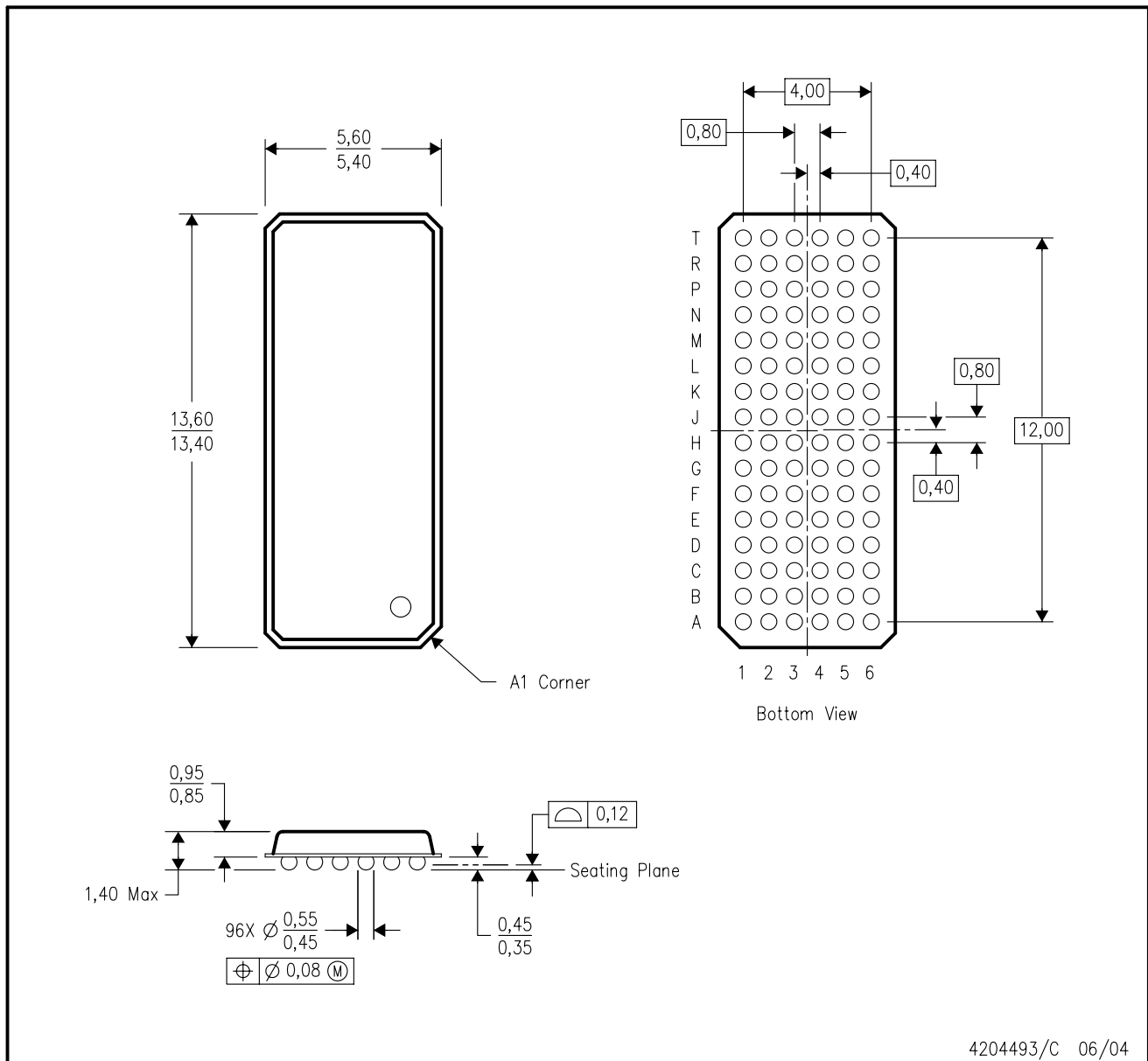
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation CC.
  - D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

ZKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation CC.
  - D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).

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